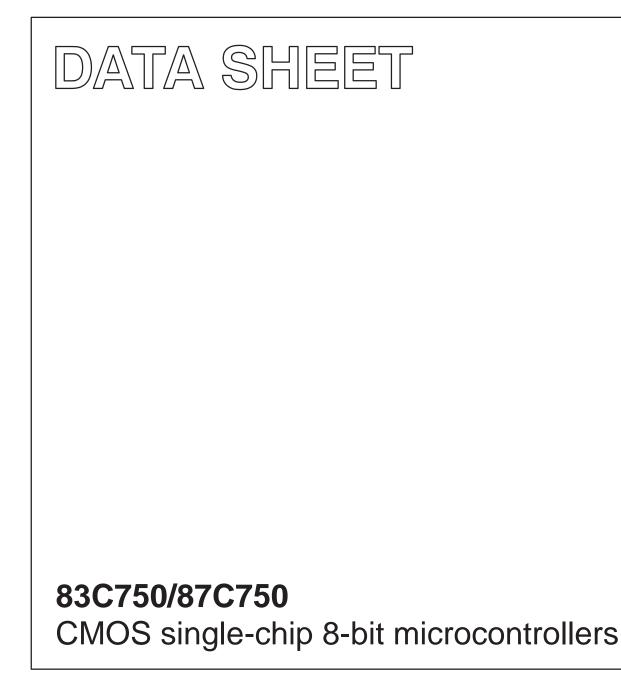
INTEGRATED CIRCUITS



Product specification IC20 Data Handbook 1996 Aug 16



Philips Semiconductors

83C750/87C750

DESCRIPTION

The Philips 8XC750 offers the advantages of the 80C51 architecture in a small package and at low cost.

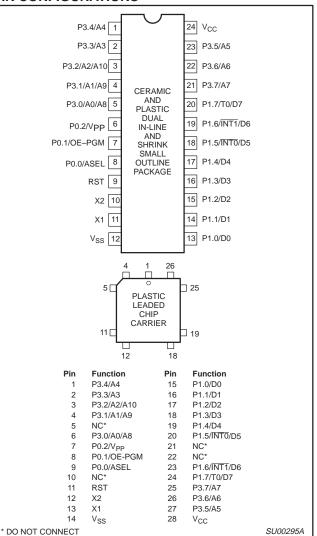
The 8XC750 Microcontroller is fabricated with Philips high-density CMOS technology. Philips epitaxial substrate minimizes CMOS latch-up sensitivity.

The 87C750 contains a 1k \times 8 EPROM, a 64 \times 8 RAM, 19 I/O lines, a 16-bit auto-reload counter/timer, a five-source, fixed-priority level interrupt structure and an on-chip oscillator.

FEATURES

- 80C51 based architecture
- Wide oscillator frequency range—up to 40MHz
- Small package sizes
 - 24-pin DIP (300 mil "skinny DIP")
 - 24-pin Shrink Small Outline Package
 - 28-pin PLCC
- 87C750 available in erasable quartz lid or one-time programmable plastic packages
- Low power consumption:
 - Normal operation: less than 11mA @ 5V, 12MHz
 - Idle mode
 - Power-down mode
- 1k × 8 EPROM (87C750)
- 64 × 8 RAM
- 16-bit auto reloadable counter/timer
- Boolean processor
- CMOS and TTL compatible
- Well suited for logic replacement, consumer and industrial applications
- LED drive outputs

PIN CONFIGURATIONS



ORDERING INFORMATION

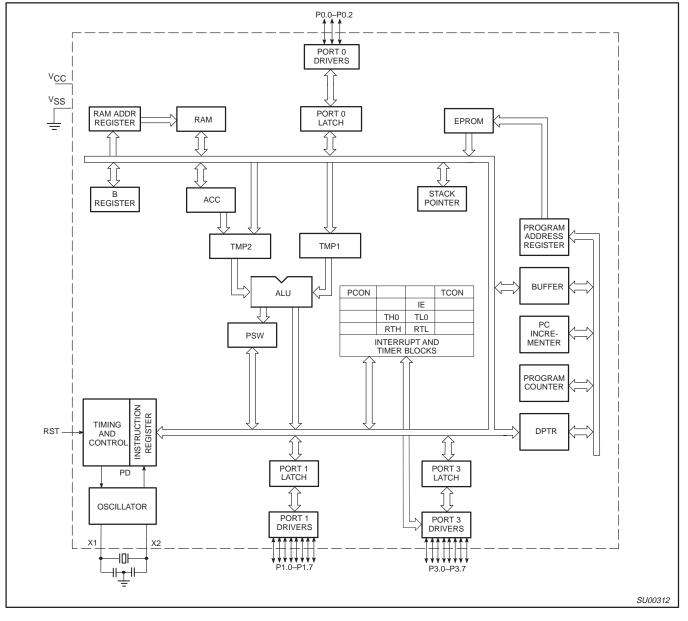
ROM	EPROM ¹		TEMPERATURE RANGE °C AND PACKAGE	FREQUENCY	DRAWING NUMBER
	P87C750EBF FA	UV	0 to +70, Ceramic Dual In-line Package	3.5 to 16MHz	0586B
	P87C750EFF FA	UV	–40 to +85, Ceramic Dual In-line Package	3.5 to 16MHz	0586B
P83C750EBP N	P87C750EBP N	OTP	0 to +70, Plastic Dual In-line Package	3.5 to 16MHz	SOT222-1
P83C750EFP N	P87C750EFP N	OTP	–40 to +85, Plastic Dual In-line Package	3.5 to 16MHz	SOT222-1
P83C750EBA A	P87C750EBA A	OTP	0 to +70, Plastic Lead Chip Carrier	3.5 to 16MHz	SOT261-3
P83C750EFA A	P87C750EFA A	OTP	–40 to +85, Plastic Lead Chip Carrier	3.5 to 16MHz	SOT261-3
P83C750EBD DB	P87C750EBD DB	OTP	0 to +70, Shrink Small Outline Package	3.5 to 16MHz	SOT340-1
P83C750PBP N	P87C750PBP N	OTP	0 to +70, Plastic Dual In-line Package	3.5 to 40MHz	SOT222-1
P83C750PFP N	P87C750PFP N	OTP	–40 to +85, Plastic Dual In-line Package	3.5 to 40MHz	SOT222-1
P83C750PBA A	P87C750PBA A	OTP	0 to +70, Plastic Lead Chip Carrier	3.5 to 40MHz	SOT261-3
P83C750PFA A	P87C750PFA A	OTP	-40 to +85, Plastic Lead Chip Carrier	3.5 to 40MHz	SOT261-3
	P87C750PBF FA	UV	0 to +70, Ceramic Dual In-line Package	3.5 to 40MHz	0586B
	P87C750PFF FA	UV	–40 to +85, Ceramic Dual In-line Package	3.5 to 40MHz	0586B

NOTE:

1. OTP = One Time Programmable EPROM. UV = UV Erasable EPROM.

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BLOCK DIAGRAM



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PIN DESCRIPTIONS

PIN NO.				
MNEMONIC	DIP/ SSOP	LCC	TYPE	NAME AND FUNCTION
V _{SS}	12	14	I	Circuit Ground Potential
V _{CC}	24	28	1	Supply voltage during normal, idle, and power-down operation.
P0.0-P0.2	8-6	9-7	I/O	Port 0: Port 0 is a 3-bit open-drain, bidirectional port. Port 0 pins that have 1s written to them float, and in that state can be used as high-impedance inputs. These pins are driven low if the port register bit is written with a 0. The state of the pin can always be read from the port register by the program.
				P0.0, P0.1, and P0.2 are open drain bidirectional I/O pins with the electrical characteristics listed in the tables that follow. While these differ from "standard TTL" characteristics, they are close enough for the pins to still be used as general-purpose I/O. Port 0 also provides alternate functions for programming the EPROM memory as follows:
	6	7	N/A	VPP (P0.2) – Programming voltage input. (See Note 1.)
	7	8	I	OE/PGM (P0.1) – Input which specifies verify mode (output enable) or the program mode. OE/PGM = 1 output enabled (verify mode). OE/PGM = 0 program mode.
	8	9	I	ASEL (P0.0) – Input which indicates which bits of the EPROM address are applied to port 3. ASEL = 0 low address byte available on port 3. ASEL = 1 high address byte available on port 3 (only the three least significant bits are used).
P1.0-P1.7	13-20	15-20, 23, 24	I/O	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 1 pins that are externally pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I _{IL}). Port 1 serves to output the addressed EPROM contents in the verify mode and accepts as inputs the value to program into the selected address during the program mode. Port 1 also serves the special function features of the 80C51 family as listed below:
	18	20	1	INTO (P1.5): External interrupt.
	19	23	1	INT1 (P1.6): External interrupt.
	20	24	I I .	T0 (P1.7): Timer 0 external input.
P3.0-P3.7	5-1, 23-21	6, 4-1, 27-25	I/O	Port 3 : Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 3 pins that are externally being pulled low will source current because of the pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 3 also functions as the address input for the EPROM memory location to be programmed (or verified). The 10-bit address is multiplexed into this port as specified by P0.0/ASEL.
RST	9	11	I	Reset: A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on RESET using only an external capacitor to V_{CC} . After the device is reset, a 10-bit serial sequence, sent LSB first, applied to RESET, places the device in the programming state allowing programming address, data and V_{PP} to be applied for programming or verification purposes. The RESET serial sequence must be synchronized with the X1 input.
X1	11	13	I	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits. X1 also serves as the clock to strobe in a serial bit stream into RESET to place the device in the programming state.
X2	10	12	0	Crystal 2: Output from the inverting oscillator amplifier.

NOTE:

 When P0.2 is at or close to 0 Volt, it may affect the internal ROM operation. We recommend that P0.2 be tied to V_{CC} via a small pull-up (e.g., 2kΩ).

OSCILLATOR CHARACTERISTICS

X1 and X2 are the input and output, respectively, of an inverting amplifier which can be configured for use as an on-chip oscillator.

To drive the device from an external clock source, X1 should be driven while X2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

RESET

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To insure a good power-up reset, the RST pin must be high long

enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles. At power-up, the voltage on V_{CC} and RST must come up at the same time for a proper start-up.

IDLE MODE

In idle mode, the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

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POWER-DOWN MODE

In the power-down mode, the oscillator is stopped and the instruction to invoke power-down is the last instruction executed. Only the contents of the on-chip RAM are preserved. A hardware reset is the only way to terminate the power-down mode. the control bits for the reduced power modes are in the special function register PCON.

Table 1.External Pin Status During Idle and
Power-Down Modes

MODE	Port 0	Port 1	Port 2
Idle	Data	Data	Data
Power-down	Data	Data	Data

DIFFERENCES BETWEEN THE 8XC750 AND THE 80C51

Program Memory

On the 8XC750, program memory is 1024 bytes long and is not externally expandable, so the 80C51 instructions MOVX, LJMP, and LCALL are not implemented. The only fixed locations in program memory are the addresses at which execution is taken up in response to reset and interrupts, which are as follows:

Prog	ra	an	n	Memory

Event	Address
Reset	000
External INT0	003
Counter/timer 0	00B
External INT1	013

Counter/Timer Subsystem

Timer/Counter

The 8XC750 has one timers: a 16-bit timer/counter. The 16-bit timer/counter's operation is similar to mode 2 operation on the 80C51, but is extended to 16 bits. The timer/counter is clocked by either 1/12 the oscillator frequency or by transitions on the T0 pin. The C/T pin in special function register TCON selects between these two modes. When the TCON TR bit is set, the timer/counter is enabled. Register pair TH and TL are incremented by the clock source. When the register pair overflows, the register pair is reloaded with the values in registers RTH and RTL. The value in the reload registers is left unchanged. See the 83C750 counter/timer block diagram in Figure 1. The TF bit in special function register

TCON is set on counter overflow and, if the interrupt is enabled, will generate an interrupt.

TCON Register

MSB							LSB			
GATE	C/T	TF	TR	IE0	IT0	IE1	IT1			
GATE	 ATE 1 – Timer/counter is enabled only when INT0 pin is high, and TR is 1. 0 – Timer/counter is enabled when TR is 1. 									
C/T		Counter/tii Timer ope								
TF	0 - 0	1 – Set on overflow of TH.								
TR	1 — T	imer/cou imer/cou	nter enab							
IE0	1 — E	Edge dete	cted in II	NTO.						
IT0		1 – INTO is edge triggered.								
IE1	1 — E	dge dete	cted on I	NT1.						
IT1		NT1 is ed NT1 is lev	0 00							
							-			

These flags are functionally identical to the corresponding 80C51 flags, except that there is only one timer on the 83C750 and the flags are therefore combined into one register.

Note that the positions of the IE0/IT0 and IE1/IT1 bits are transposed from the positions used in the standard 80C51 TCON register.

Interrupt Subsystem – Fixed Priority

The IP register and the 2-level interrupt system of the 80C51 are eliminated. Simultaneous interrupt conditions are resolved by a single-level, fixed priority as follows:

Highest priority: Pin INT0 Counter/timer flag 0 Pin INT1

Special Function Register Addresses

Special function registers for the 8XC750 are identical to those of the 80C51, except for the changes listed below:

80C51 special function registers not present in the 8XC750 are TMOD (89), P2 (A0) and IP (B8). The 80C51 registers TH1 and TL1 are replaced with the 87C750 registers RTH and RTL respectively (refer to Table 2).

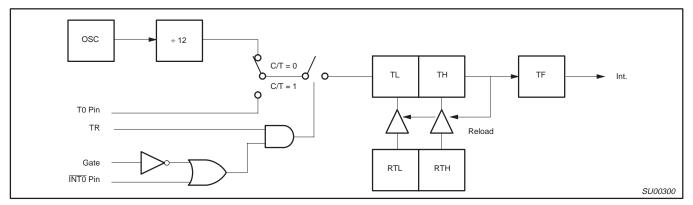


Figure 1. 83C751 Counter/Timer Block Diagram

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CMOS single-chip 8-bit microcontrollers

Table 2.		DIRECT							FUNCTIO	N	RESET
SYMBOL	DESCRIPTION	ADDRESS	MSB		55, 5 HVID	UL, UK A				LSB	VALUE
ACC*	Accumulator	E0H	E7	E6	E5	E4	E3	E2	E1	E0	00H
B*	B register	F0H	F7	F6	F5	F4	F3	F2	F1	F0	00H
DPTR:	Data pointer (2 bytes)										
DPH DPL	High byte Low byte	83H 82H									00H 00H
			AF	AE	AD	AC	AB	AA	A9	A8	
IE*#	Interrupt enable	A8H	EA	-	-	-	-	EX1	ET0	EX0	00H
								82	81	80	
P0*#	Port 0	80H	-	_	_	_	_	_	-	_	xxxxx111B
			97	96	95	94	93	92	91	90	
P1*	Port 1	90H	TO	INT1	INTO	_	-	-	-	-	FFH
P3*	Port 3	B0H	B7	B6	B5	B4	B3	B2	B1	B0	FFH
											1
PCON#	Power control	87H	-	-	-	-	-	-	PD	IDL	xxxxxx00B
					-						1
			D7	D6	D5	D4	D3	D2	D1	D0	
PSW*	Program status word	D0H	CY	AC	F0	RS1	RS0	OV	-	Р	00H
SP	Stack pointer	81H									07H
			8F	8E	8D	8C	8B	8A	89	88	4
TCON*#	Timer/counter control	88H	GATE	C/T	TF	TR	IE0	IT0	IE1	IT1	00H
TL#	Timer low byte	8AH									00H
TH#	Timer high byte	8CH									00H
RTL#	Timer low reload	8BH									00H
RTH#	Timer high reload	8DH									00H

Table 2. 87C750 Special Function Registers

SFRs are bit addressable.

SFRs are modified from or added to the 80C51 SFRs.

ABSOLUTE MAXIMUM RATINGS^{1, 2}

PARAMETER	RATING	UNIT
Storage temperature range	-65 to +150	°C
Voltage from V_{CC} to V_{SS}	-0.5 to +6.5	V
Voltage from any pin to V _{SS} (except V _{PP})	–0.5 to V _{CC} + 0.5	V
Power dissipation	1.0	W
Voltage on V _{PP} pin to V _{SS}	0 to +13.0	V
Maximum I _{OL} per I/O pin	10	mA

NOTES:

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.
 This is a stress rating only and the stress rating on the st

2. This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.

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DC ELECTRICAL CHARACTERISTICS

 $T_{amb} = 0^{\circ}C$ to +70°C or -40°C to +85°C, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V^{1}$

		TEST	LIN		
SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V _{IL} V _{IH} V _{IH1}	Input low voltage Input high voltage, except X1, RST Input high voltage, X1, RST		-0.5 0.2V _{CC} +0.9 0.7V _{CC}	0.2V _{DD} -0.1 V _{CC} +0.5 V _{CC} +0.5	V V V
V _{OL} V _{OL1}	Output low voltage, ports 1 and 3 Output low voltage, port 0	$I_{OL} = 1.6 \text{mA}^2$ $I_{OL} = 3.2 \text{mA}^2$		0.45 0.45	V V
V _{OH}	Output high voltage, ports 1 and 3	I _{OH} = -60μA I _{OH} = -25μA I _{OH} = -10μA	2.4 0.75V _{CC} 0.9V _{CC}		V V V
С	Capacitance			10	pF
Ι _{ΙL} Ι _{ΤL}	Logical 0 input current, ports 1 and 3 Logical 1 to 0 transition current, ports 1 and 3 ³ Input leakage current, port 0	$V_{IN} = 0.45V \\ V_{IN} = 2V (0 \text{ to } +70^{\circ}\text{C}) \\ V_{IN} = 2V (-40 \text{ to } +85^{\circ}\text{C}) \\ 0.45 < V_{IN} < V_{CC}$		-50 -650 -750 ±10	μΑ μΑ μΑ μΑ
R _{RST}	Internal pull-down resistor		25	175	kΩ
C _{IO}	Pin capacitance	Test freq = 1MHz, T _{amb} = 25°C		10	pF
I _{PD}	Power-down current ⁴	$V_{CC} = 2$ to V_{CC} max		50	μA
V _{PP}	V _{PP} program voltage	$V_{SS} = 0V$ $V_{CC} = 5V\pm10\%$ $T_{amb} = 21^{\circ}C \text{ to } 27^{\circ}C$	12.5	13.0	V
I _{PP}	Program current	V _{PP} = 13.0V		50	mA
I _{CC}	Supply current (see Figure 3) ^{5, 6}				

NOTES:

Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise 1. noted.

Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows: Maximum I_{OL} per port pin: 10mA (NOTE: This is 85°C spec.)

Maximum I_{OL} per port pin: 10mA (NOTE: This is 85°C spec.) Maximum I_{OL} per 8-bit port: 26mA Maximum total I_{OL} for all outputs: 67mA If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

3. Pins of ports 1 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when VIN is approximately 2V.

Power-down I_{CC} is measured with all output pins disconnected; port 0 = V_{CC}; X2, X1 n.c.; RST = V_{SS}.

Active I_{CC} is measured with all output pins disconnected; X1 driven with t_{CLCH}, t_{CHCL} = 5ns, V_{IL} = V_{SS} + 0.5V, V_{IH} = V_{CC} - 0.5V; X2 n.c.; RST = port 0 = V_{CC}. I_{CC} will be slightly higher if a crystal oscillator is used. Idle I_{CC} is measured with all output pins disconnected; X1 driven with t_{CLCH}, t_{CHCL} = 5ns, V_{IL} = V_{SS} + 0.5V, V_{IH} = V_{CC} - 0.5V; X2 n.c.; port 0 = V_{CC}; RST = V_{SS}. 5.

6.

AC ELECTRICAL CHARACTERISTICS

 $T_{amb} = 0^{\circ}C$ to +70°C or -40°C to +85°C, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V^{1, 2}$

			VARIABLE CLOCK				
SYMBOL	PARAMETER	MIN	MAX	MIN	MAX	UNIT	
1/t _{CLCL}	Oscillator frequency:	3.5	16	3.5	40	MHz	
External (Clock (Figure 2)						
t _{CHCX}	High time	20		10		ns	
t _{CLCX}	Low time	20		10		ns	
t _{CLCH}	Rise time		20		20	ns	
t _{CHCL}	Fall time		20		20	ns	

NOTES:

1. Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

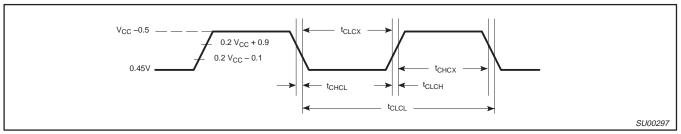
2. Load capacitance for ports = 80pF.

EXPLANATION OF THE AC SYMBOLS

In defining the clock waveform, care must be taken not to exceed the MIN or MAX limits of the AC electrical characteristics table. Each timing symbol has five characters. The first character is always 't' (= time). The other characters, depending on their positions, indicate the name of a signal or the logical status of that signal. The designations are:

- C Clock
- D Input data

- H Logic level high
- L Logic level low
- Q Output data
- T Time V – Valid
- X No longer a valid logic level
- Z Float
- Z FI





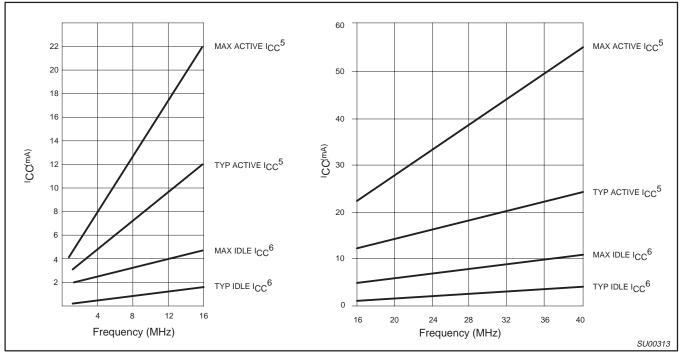


Figure 3. I_{CC} vs. Frequency Maximum I_{CC} values taken at V_{CC} max and worst case temperature. Typical I_{CC} values taken at $V_{CC} = 5.0V$ and $25^{\circ}C$. Notes 5 and 6 refer to DC Electrical Characteristics.

ROM CODE SUBMISSION

When submitting ROM code for the 80C750, the following must be specified:

1. 1k byte user ROM data

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to 03FFH	DATA	7:0	User ROM Data

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87C750 PROGRAMMING CONSIDERATIONS

EPROM Characteristics

The 87C750 is programmed by using a modified Quick-Pulse Programming algorithm similar to that used for devices such as the 87C451 and 87C51. It differs from these devices in that a serial data stream is used to place the 87C750 in the programming mode.

Figure 4 shows a block diagram of the programming configuration for the 87C750. Port pin P0.2 is used as the programming voltage supply input (V_{PP} signal). Port pin P0.1 is used as the program (PGM/) signal. This pin is used for the 25 programming pulses.

Port 3 is used as the address input for the byte to be programmed and accepts both the high and low components of the eleven bit address. Multiplexing of these address components is performed using the ASEL input. The user should drive the ASEL input high and then drive port 3 with the high order bits of the address. ASEL should remain high for at least 13 clock cycles. ASEL may then be driven low which latches the high order bits of the address internally. the high address should remain on port 3 for at least two clock cycles after ASEL is driven low. Port 3 may then be driven with the low byte of the address. The low address will be internally stable 13 clock cycles later. The address will remain stable provided that the low byte placed on port 3 is held stable and ASEL is kept low. **Note:** ASEL needs to be pulsed high only to change the high byte of the address.

Port 1 is used as a bidirectional data bus during programming and verify operations. During programming mode, it accepts the byte to be programmed. During verify mode, it provides the contents of the EPROM location specified by the address which has been supplied to Port 3.

The XTAL1 pin is the oscillator input and receives the master system clock. This clock should be between 1.2 and 6MHz.

The RESET pin is used to accept the serial data stream that places the 87C750 into various programming modes. This pattern consists of a 10-bit code with the LSB sent first. Each bit is synchronized to the clock input, X1.

Programming Operation

Figures 5 and 6 show the timing diagrams for the program/verify cycle. RESET should initially be held high for at least two machine cycles. P0.1 (PGM/) and P0.2 (V_{PP}) will be at V_{OH} as a result of the RESET operation. At this point, these pins function as normal quasi-bidirectional I/O ports and the programming equipment may pull these lines low. However, prior to sending the 10-bit code on the RESET pin, the programming equipment should drive these pins high (V_{IH}). The RESET pin may now be used as the serial data input for the data stream which places the 87C750 in the programming mode. Data bits are sampled during the clock high time and thus should only change during the time that the clock is low. Following transmission of the last data bit, the RESET pin should be held low.

Next the address information for the location to be programmed is placed on port 3 and ASEL is used to perform the address multiplexing, as previously described. At this time, port 1 functions as an output.

A high voltage V_{PP} level is then applied to the V_{PP} input (P0.2). (This sets Port 1 as an input port). The data to be programmed into the EPROM array is then placed on Port 1. This is followed by a series of programming pulses applied to the PGM/ pin (P0.1). These pulses are created by driving P0.1 low and then high. This pulse is repeated until a total of 25 programming pulses have occurred. At the conclusion of the last pulse, the PGM/ signal should remain high.

The V_{PP} signal may now be driven to the V_{OH} level, placing the 87C750 in the verify mode. (Port 1 is now used as an output port). After four machine cycles (48 clock periods), the contents of the addressed location in the EPROM array will appear on Port 1.

The next programming cycle may now be initiated by placing the address information at the inputs of the multiplexed buffers, driving the V_{PP} pin to the V_{PP} voltage level, providing the byte to be programmed to Port1 and issuing the 26 programming pulses on the PGM/ pin, bringing V_{PP} back down to the V_C level and verifying the byte.

Programming Modes

The 87C750 has four programming features incorporated within its EPROM array. These include the USER EPROM for storage of the application's code, a 16-byte encryption key array and two security bits. Programming and verification of these four elements are selected by a combination of the serial data stream applied to the RESET pin and the voltage levels applied to port pins P0.1 and P0.2. The various combinations are shown in Table 3.

Encryption Key Table

The 87C750 includes a 16-byte EPROM array that is programmable by the end user. The contents of this array can then be used to encrypt the program memory contents during a program memory verify operation. When a program memory verify operation is performed, the contents of the program memory location is XNOR'ed with one of the bytes in the 16-byte encryption table. The resulting data pattern is then provided to port 1 as the verify data. The encryption mechanism can be disable, in essence, by leaving the bytes in the encryption table in their erased state (FFH) since the XNOR product of a bit with a logical one will result in the original bit. The encryption bytes are mapped with the code memory in 16-byte groups. the first byte in code memory will be encrypted with the first byte in the encryption table; the second byte in code memory will be encrypted with the second byte in the encryption table and so forth up to and including the 16the byte. The encryption repeats in 16-byte groups; the 17th byte in the code memory will be encrypted with the first byte in the encryption table, and so forth.

Security Bits

Two security bits, security bit 1 and security bit 2, are provided to limit access to the USER EPROM and encryption key arrays. Security bit 1 is the program inhibit bit, and once programmed performs the following functions:

- 1. Additional programming of the USER EPROM is inhibited.
- 2. Additional programming of the encryption key is inhibited.
- 3. Verification of the encryption key is inhibited.
- Verification of the USER EPROM and the security bit levels may still be performed.

(If the encryption key array is being used, this security bit should be programmed by the user to prevent unauthorized parties from reprogramming the encryption key to all logical zero bits. Such programming would provide data during a verify cycle that is the logical complement of the USER EPROM contents).

Security bit 2, the verify inhibit bit, prevents verification of both the USER EPROM array and the encryption key arrays. The security bit levels may still be verified.

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Programming and Verifying Security Bits

Security bits are programmed employing the same techniques used to program the USER EPROM and KEY arrays using serial data streams and logic levels on port pins indicated in Table 3. When programming either security bit, it is not necessary to provide address or data information to the 87C750 on ports 1 and 3.

Verification occurs in a similar manner using the RESET serial stream shown in Table 3. Port 3 is not required to be driven and the results of the verify operation will appear on ports 1.6 and 1.7.

Ports 1.7 contains the security bit 1 data and is a logical one if programmed and a logical zero if erased. Likewise, P1.6 contains the security bit 2 data and is a logical one if programmed and a logical zero if erased.

Erasure Characteristics

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelengths shorter than approximately 4,000 angstroms. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room level fluorescent lighting) could cause inadvertent erasure. For this and secondary effects, it is recommended that an opaque label be placed over the window. For elevated temperature or environments where solvents are being used, apply Kapton tape Flourless part number 2345-5 or equivalent.

The recommended erasure procedure is exposure to ultraviolet light (at 2537 angstroms) to an integrated dose of at least 15W-s/cm². Exposing the EPROM to an ultraviolet lamp of 12,000 μ W/cm² rating for 20 to 39 minutes, at a distance of about 1 inch, should be sufficient.

Erasure leaves the array in an all 1s state.

Table 3. Implementing Program/Verify Modes

OPERATION	SERIAL CODE	P0.1 (PGM/)	P0.2 (V _{PP})
Program user EPROM	296H	_1	V _{PP}
Verify user EPROM	296H	V _{IH}	VIH
Program key EPROM	292H	_1	V _{PP}
Verify key EPROM	292H	VIH	V _{IH}
Program security bit 1	29AH	_1	V _{PP}
Program security bit 2	298H	_1	V _{PP}
Verify security bits	29AH	V _{IH}	V _{IH}

NOTE:

1. Pulsed from V_{IH} to V_{IL} and returned to V_{IH} .

EPROM PROGRAMMING AND VERIFICATION

 $T_{amb} = 21^{\circ}C \text{ to } +27^{\circ}C, V_{CC} = 5V \pm 10\%, V_{SS} = 0V$

SYMBOL	PARAMETER	MIN	MAX	UNIT
1/t _{CLCL}	Oscillator/clock frequency	1.2	6	MHz
t _{AVGL} 1	Address setup to P0.1 (PROG-) low	10μs + 24t _{CLCL}		
t _{GHAX}	Address hold after P0.1 (PROG-) high	48t _{CLCL}		
t _{DVGL}	Data setup to P0.1 (PROG-) low	38t _{CLCL}		
t _{DVGL}	Data setup to P0.1 (PROG-) low	38t _{CLCL}		
t _{GHDX}	Data hold after P0.1 (PROG-) high	36t _{CLCL}		
t _{SHGL}	V _{PP} setup to P0.1 (PROG–) low	10		μs
t _{GHSL}	V _{PP} hold after P0.1 (PROG–)	10		μs
t _{GLGH}	P0.1 (PROG–) width	90	110	μs
t _{AVQV} ²	V _{PP} low (V _{CC}) to data valid		48t _{CLCL}	
t _{GHGL}	P0.1 (PROG–) high to P0.1 (PROG–) low	10		μs
t _{SYNL}	P0.0 (sync pulse) low	4t _{CLCL}		
t _{SYNH}	P0.0 (sync pulse) high	8t _{CLCL}		
t _{MASEL}	ASEL high time	13t _{CLCL}		
t _{MAHLD}	Address hold time	2t _{CLCL}		
t _{HASET}	Address setup to ASEL	13t _{CLCL}		
t _{ADSTA}	Low address to valid data		48t _{CLCL}	

NOTES:

1. Address should be valid at least $24t_{CLCL}$ before the rising edge of P0.2 (V_{PP}).

2. For a pure verify mode, i.e., no program mode in between, t_{AVQV} is $14t_{CLCL}$ maximum.

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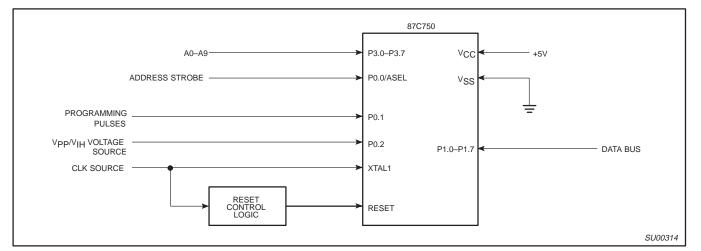


Figure 4. Programming Configuration

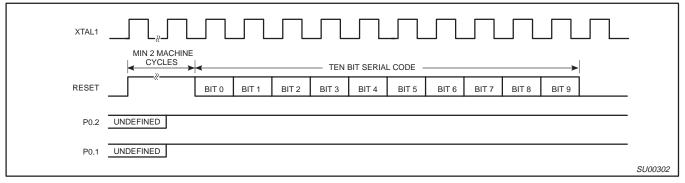


Figure 5. Entry into Program/Verify Modes

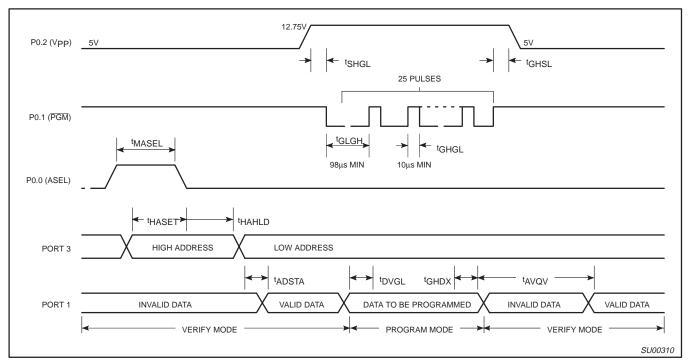
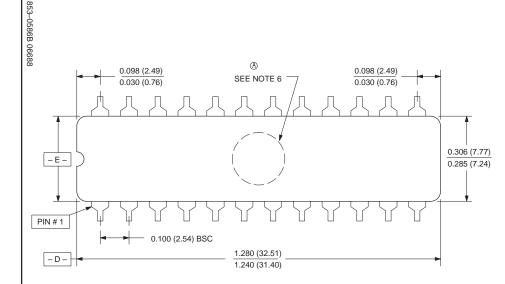


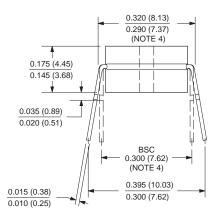
Figure 6. Program/Verify Cycle

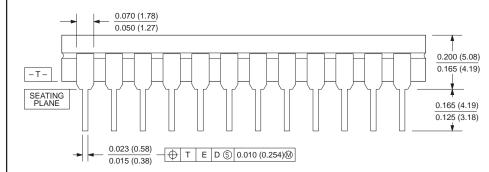
11



NOTES:

- 1. Controlling dimension: Inches. Millimeters are shown in parentheses.
- 2. Dimension and tolerancing per ANSI Y14. 5M-1982.
- 3. "T", "D", and "E" are reference datums on the body and include allowance for glass overrun and meniscus on the seal line, and lid to base mismatch.
- 4. These dimensions measured with the leads constrained to be perpendicular to plane T.
- 5. Pin numbers start with Pin #1 and continue counterclockwise to Pin #24 when viewed from the top.
- 6. Denotes window location for EPROM products.





83C750/87C750

CMOS

single-chip

8-bit

microcontrollers

0586B

24-PIN (300 mils wide) CERAMIC DUAL IN-LINE (F) PACKAGE (WITH WINDOW (FA) PACKAGE

seating plane

CMOS single-chip 8-bit microcontrollers

DIP24: plastic dual in-line package; 24 leads (300 mil)

D

IMENSIO	NS (mill	imetre di	mension	s are der	ived from	the orig	ginal inch	dimensi	ons)		 			
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	-		-		e 🖣				<-	\bigcirc		e 1) —		

UNIT	max.	min.	max.	b	b 1	с	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	max.
mm	4.70	0.38	3.94	1.63 1.14	0.56 0.43	0.36 0.25	31.9 31.5	6.73 6.48	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	2.05
inches	0.185	0.015	0.155	0.064 0.045	0.022 0.017	0.014 0.010	1.256 1.240	0.265 0.255	0.100	0.300	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.081

Note

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT222-1		MS-001AF				95-03-11

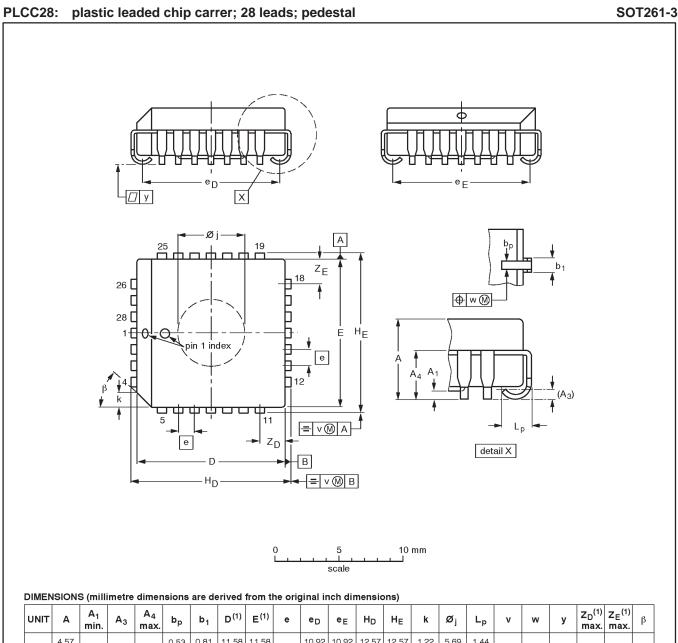
SOT222-1

83C750/87C750

ME

A

83C750/87C750



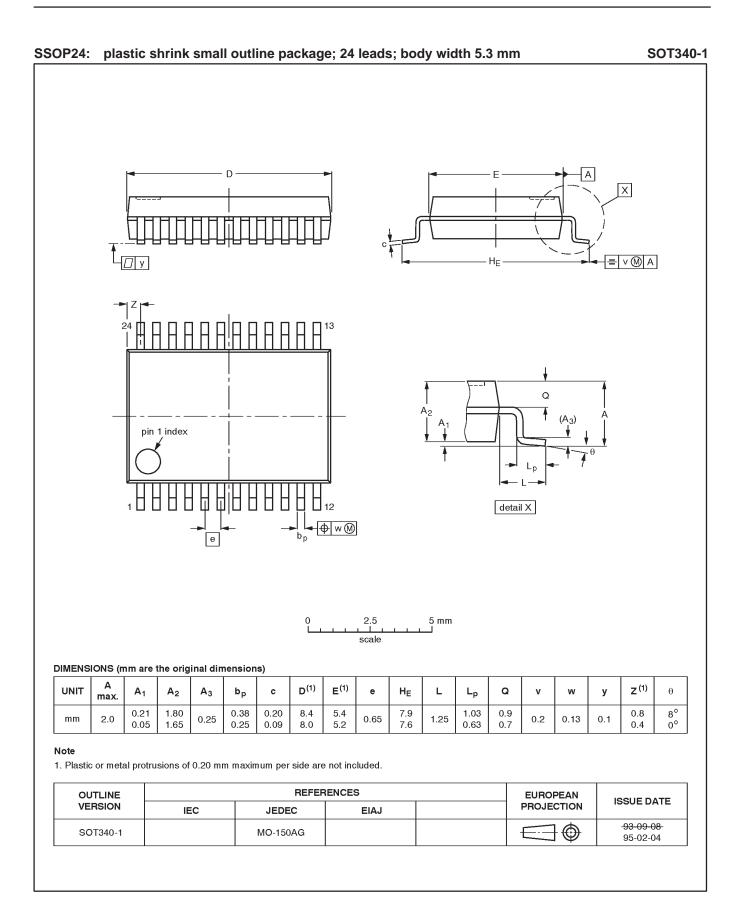
mm 4.57 4.19 0.13 0.25 3.05 0.53 0.33 0.81 0.66 11.58 1.43 12.57 1.43 0.92 1.23 12.57 1.23 12.67 1.23 12.67 1.23 1.24 1.07 1.44 1.02 0.18 0.18 0.18 0.10 2.06 inches 0.160 0.165 0.005 0.01 0.12 0.021 0.013 0.026 0.450 0.450 0.450 0.450 0.430 0.430 0.485 0.485 0.048 0.224 0.057 0.007 0.007 0.004 0.004 0.005 0.005 0.005 0.430 0.390 0.485 0.485 0.485 0.048 0.224 0.057 0.007 0.007 0.004 0.005 0.005 0.005 0.005 0.005 0.005 0.005 0.005 0.005 0.005 0.048 0.485		1111			max.									-					max.	max.		
inches 0.180 0.005 0.01 0.12 0.021 0.02 0.456 0.456 0.456 0.05 0.430 0.430 0.495 0.495 0.495 0.048 0.224 0.057 0.007 0.007 0.007 0.004 0.081	mm	101	13	0.25	3.05											0.18	0.18	0.10	2.06	2.06	45	
	inches	0.180 0.165 0.00	005	0.01				0.05	0.430 0.390	0.430 0.390	0.495 0.485	0.495 0.485	0.048 0.042	0.224 0.218	0.057 0.040	0.007	0.007	0.004	0.081	0.081	1.0	

Note

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

OUTLINE		REFER	EUROPEAN						
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE			
SOT261-3		MO-047AB				-92-11-17 95-02-25			

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1996 Aug 16

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Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.							

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